

STMicroelectronics Advances 60 GHz Contactless Communications with HPC

Operating at very high frequencies, millimeter wave devices for close-range wireless communications are complex to create and validate. STMicroelectronics (ST) meets the challenges with HPE ProLiant servers based on Intel® Xeon® Gold processors on-premises and similarly configured systems in Microsoft Azure cloud. Ansys HFSS handles ST’s electromagnetic analysis and simulation requirements. Ansys HFSS takes advantage of Intel® Advanced Vector Extensions 512 and Intel® oneAPI Math Kernel Library to keep performance high. Together, Ansys software and Intel technology-based infrastructure help ST produce innovative 60 GHz products within schedule requirements. Simulations are completed faster, leaving more time to analyze difficult aspects of the design and helping reduce validation costs.¹

“With our Intel based HPC and the performances increases of the last few years, we have been able to perform analyses that would not have been feasible before.”

Olivier Bayet, leader in silicon packaging co-design, signal integrity, and power integrity, STMicroelectronics

Products and Solutions

- [2nd Intel® Xeon® Scalable Processors](#)
- [Intel® Advanced Vector Extensions 512](#)
- [Intel® oneAPI Math Kernel Library](#)

Industry

Semiconductors

Organization Size

10,001+

Country

Switzerland

Partners

- [Ansys](#)
- [HPE](#)
- [Microsoft Azure](#)

Learn more

[Case Study](#)

¹ For more complete information about performance and benchmark results, visit <https://www.intel.com/content/www/us/en/customer-spotlight/stories/stmicroelectronics-customer-story.html>